

HOSTAFORM®

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988- POM-K, M-GNR, 03-002, GB10 POM copolymer Injection molding type, reinforced with ca. 10 % glass spheres; high resistance to thermal and oxidative degradation. UL-registration in natural and a thickness more than 0.81 mm, in black and a thickness more than 1.5 mm, as UL94 HB, temperature index UL 746 B for a thickness of 2 mm, electrical 105 °C, mechanical 95 °C (tensile impact) and 100 °C (tensile). Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1 mm. Ranges of applications: for low-warpage molded parts with higher rigidity and hardness. FMVSS = Federal Motor Vehicle Safety Standard (USA) UL = Underwriters Laboratories (USA)

#### Product information

Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load	9 190 2.16		ISO 1133
Moulding shrinkage, parallel Moulding shrinkage, normal [1]: @ 195°C	2.0 <sup>[1]</sup> 1.7 <sup>[1]</sup>		ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Ball indentation hardness, H 358/30 Poisson's ratio [C]: Calculated	7.5 17 3000 2800 1500 60 60 4 4	MPa % MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA ISO 2039-1
Thermal properties			
Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel		°C E-6/K	ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2
Thermal conductivity of melt Specific heat capacity of melt		W/(m K) J/(kg K)	ISO 22007-2 ISO 22007-4





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Flammability				
Burning Behav. at 1.5mm nom. thickn. Thickness tested			class mm	IEC 60695-11-10 IEC 60695-11-10
Burning Behav. at thickness h			class	IEC 60695-11-10
Thickness tested		0.81	mm	IEC 60695-11-10
UL recognition		yes		UL 94
Electrical properties				
Relative permittivity, 100Hz		4.3		IEC 62631-2-1
Relative permittivity, 1MHz		4.1		IEC 62631-2-1
Dissipation factor, 100Hz Dissipation factor, 1MHz		150 60	E-4 E-4	IEC 62631-2-1 IEC 62631-2-1
Volume resistivity			Ohm.m	IEC 62631-3-1
Surface resistivity		1E14		IEC 62631-3-2
Electric strength			kV/mm	IEC 60243-1
Comparative tracking index		600		IEC 60112
Physical/Other properties				
Humidity absorption, 2mm		0.15		Sim. to ISO 62
Water absorption, 2mm		0.8		Sim. to ISO 62
Density		14/0	kg/m³	ISO 1183
Injection				
Drying Recommended		no		
Drying Temperature		100		
Drying Time, Dehumidified Dryer Processing Moisture Content		3 - 4 ≤0.2		
Melt Temperature Optimum		200		
Min. melt temperature		190		
Max. melt temperature		210		
Screw tangential speed		≤0.3		
Mold Temperature Optimum		100	°C °C	
Min. mould temperature Max. mould temperature		120		
Hold pressure range		60 - 120		
Back pressure			MPa	
Ejection temperature		140	°C	
Characteristics				
Processing	Injection Moulding			
Delivery form	Pellets			
Additives	Release agent			

Special characteristics

Low Warpage





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### Additional information

Injection molding

#### Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

#### Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

#### Postprocessing

Conditioning e.g. moisturizing is not necessary.

**Processing Notes** 

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

#### Storage

The product can then be stored in standard conditions until processed.

### Automotive

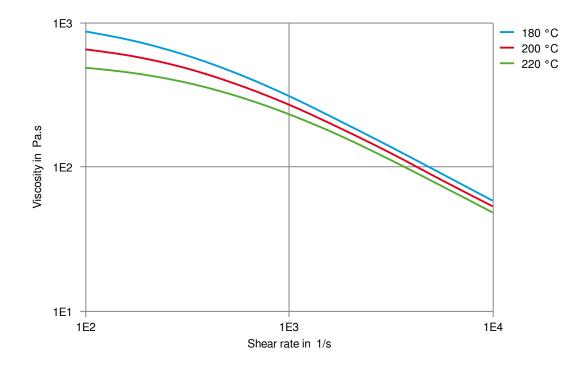
OEM Continental STANDARD TST N 055 54.13





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Viscosity-shear rate

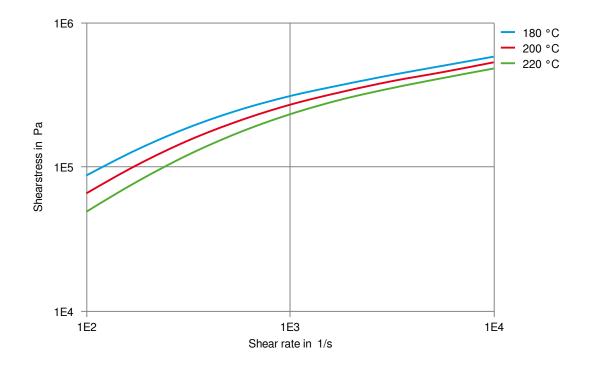






HOSTAFORM®

Shearstress-shear rate



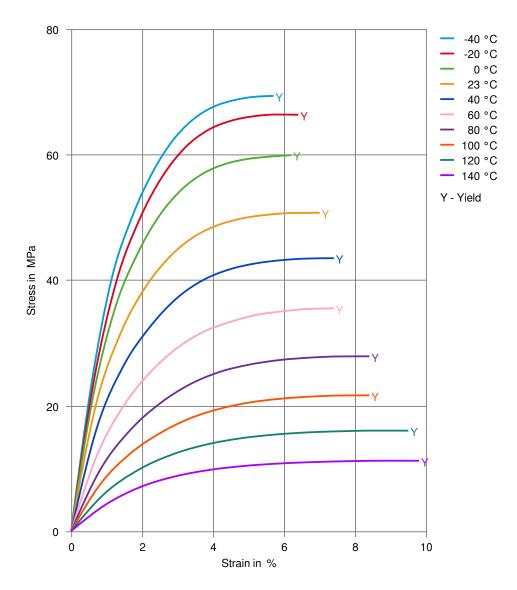




## HOSTAFORM® C 9021 GV3/10

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Stress-strain

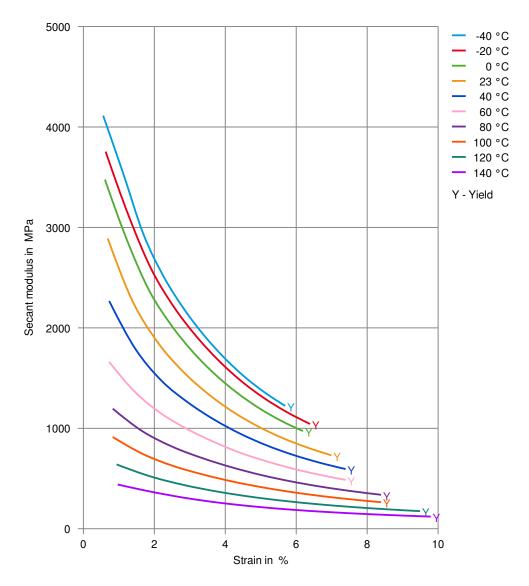






### HOSTAFORM®

#### Secant modulus-strain



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